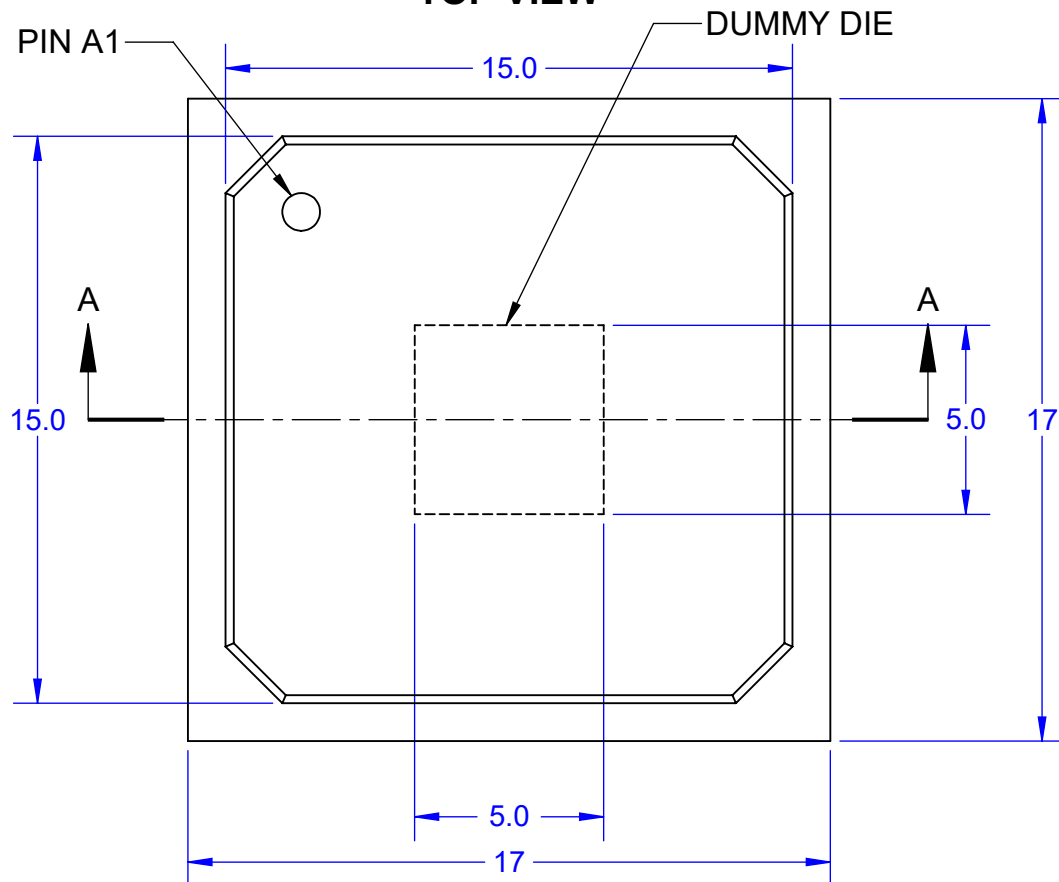
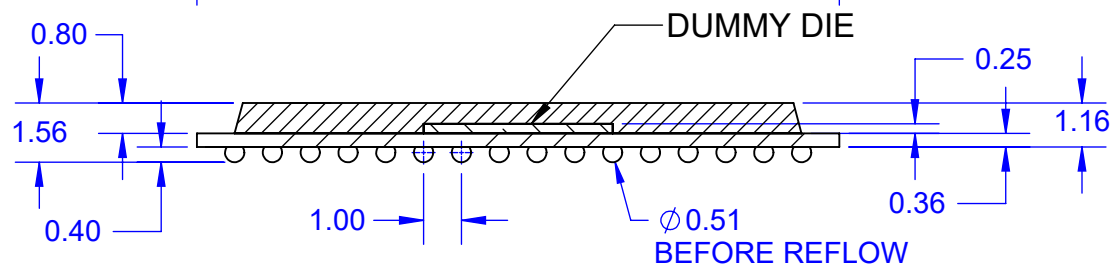
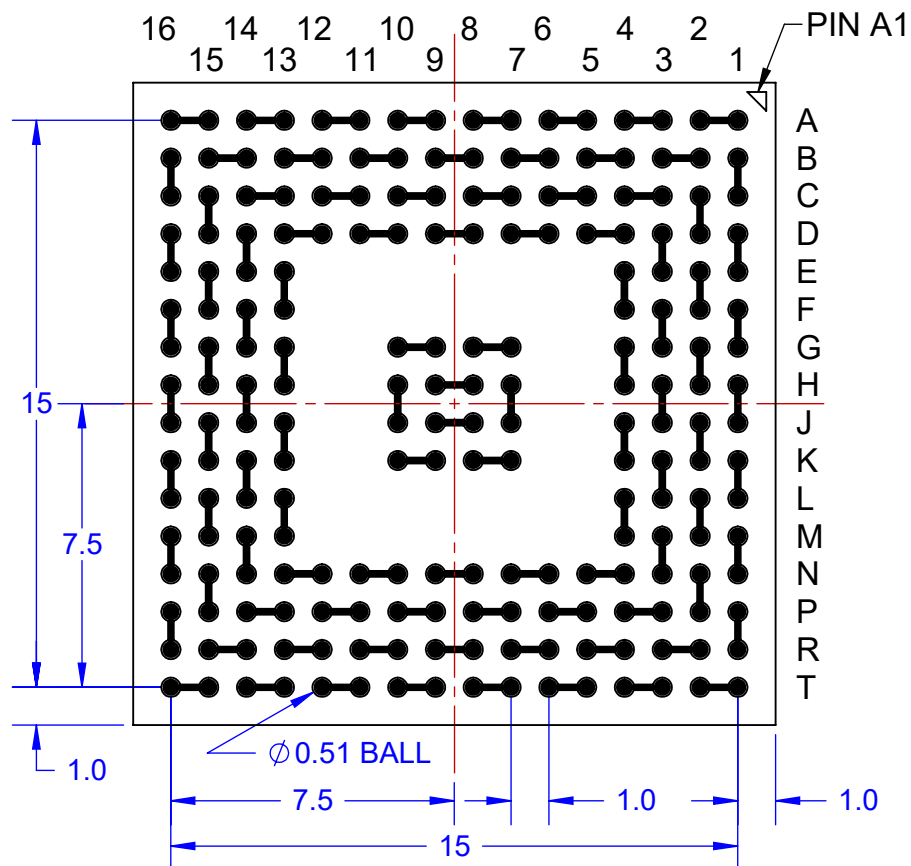


TOP VIEW



BALL VIEW



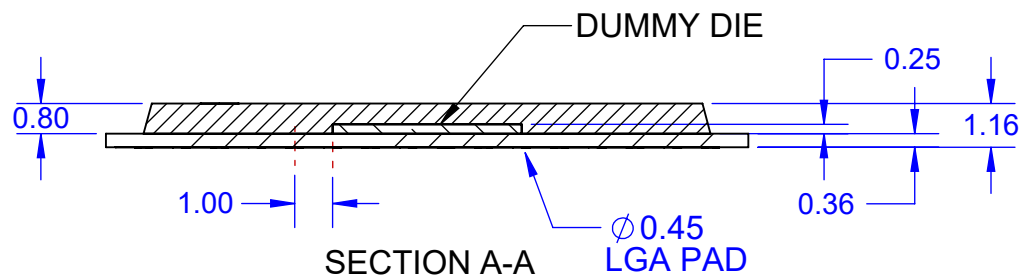
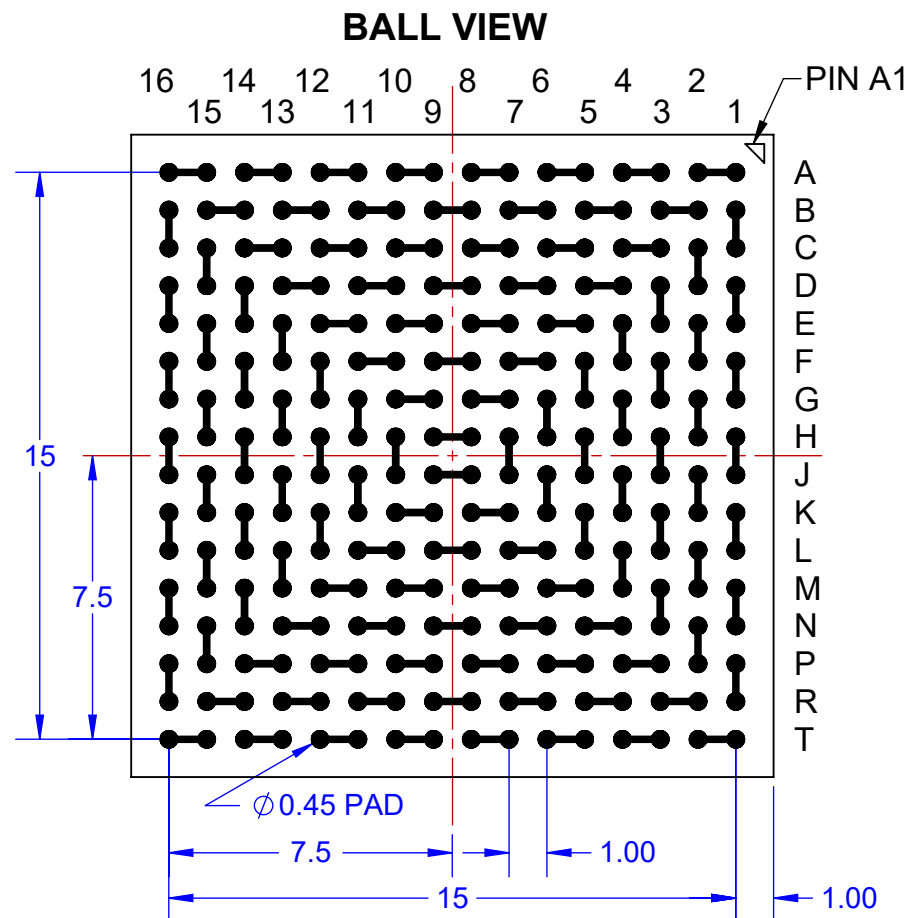
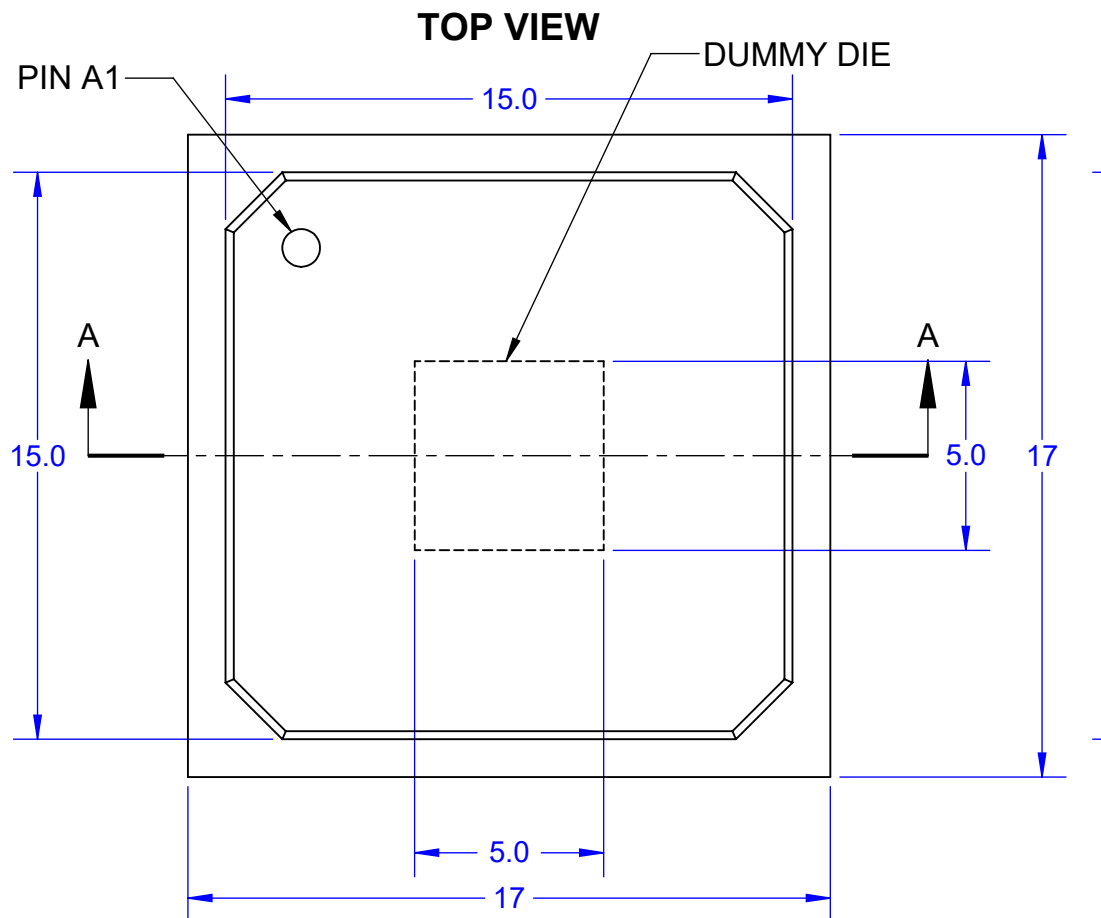
SECTION A-A

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS: MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.51mm (20 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.45mm (18 MIL).
- 5) PAD Cu DIAMETER: 0.61mm (24 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
PBGA208T1.0C-DC164AD	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
PBGA208T1.0-DC164AD	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T. Au	7/27/2025				
ENG M. Hart	7/27/2025	TITLE PBGA208T1.0C-DC164AD DAISY CHAIN DUMMY			
MFG					
QA		SCALE 5:1	SIZE A	DRAWING NO. 511641	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			
					SHEET 1 OF 6



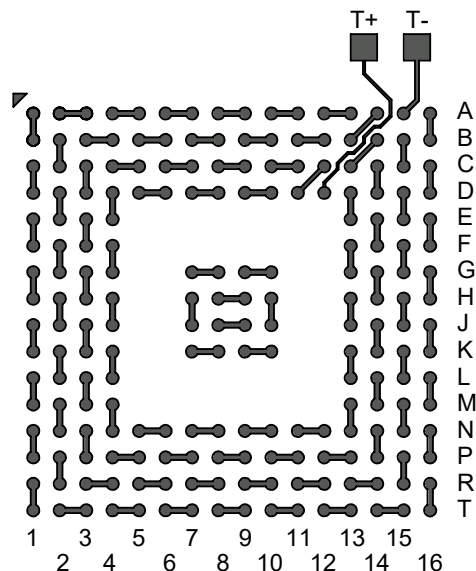
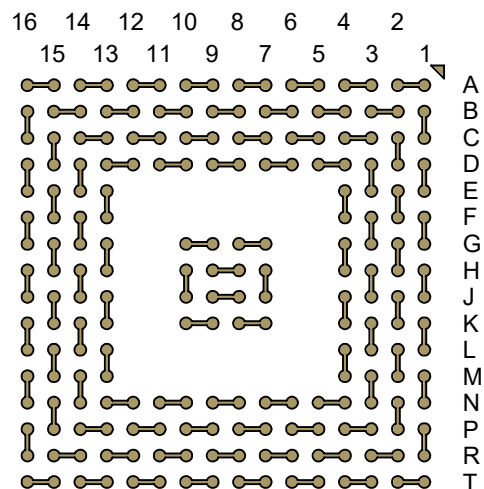
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS: MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.51mm (20 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.45mm (18 MIL).
- 5) PAD Cu DIAMETER: 0.61mm (24 MIL).
- 6) SUBSTRATE MATERIAL: BT RESIN.
- 7) DUMMY DIE OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	PAD	BALL CODE	RoHS	Si DIE
LGA256T1.0G-DC169D	Ni Au	NONE	YES	YES

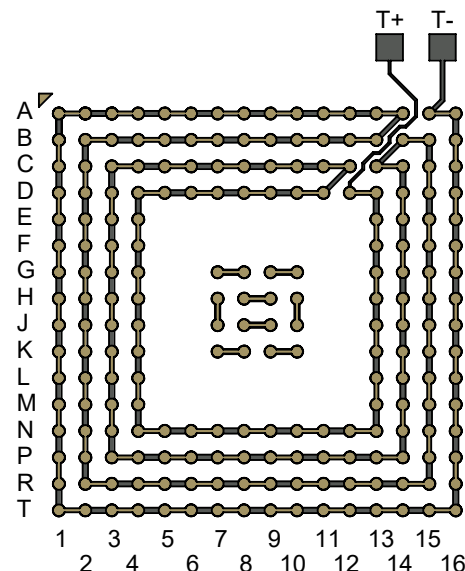
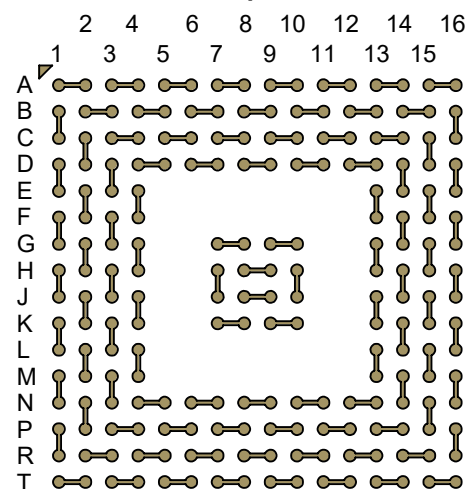
APPROVALS	DATE				
DRAWN T.Au	7/27/2025				
ENG M. Hart	7/27/2025	TITLE PGBA208T1.0C-DC164AD DAISY CHAIN DUMMY			
MFG					
QA		SCALE 5:1	SIZE A	DRAWING NO. 511641	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			
					SHEET 2 OF 6

BALL VIEW



TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.61mm (24 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.20mm (8 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.45mm (18 MIL).

TopLine®

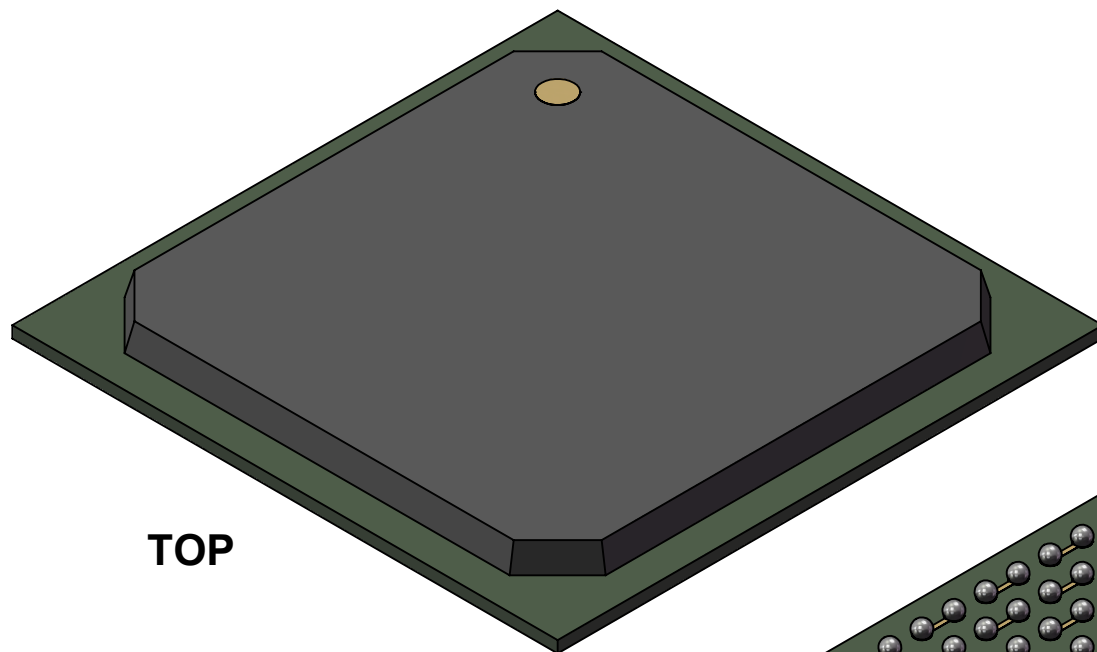
TITLE PGBA208T1.0C-DC164AD
DAISY CHAIN DUMMY

SCALE 3.5:1	SIZE A	DRAWING NO. 511641	REV A
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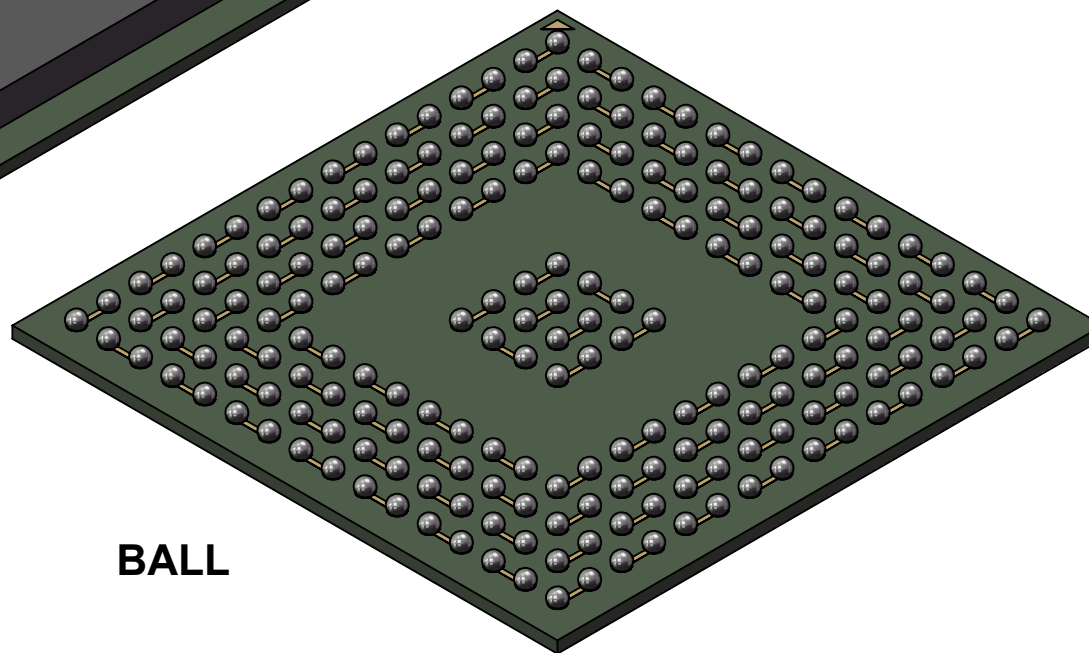
DO NOT SCALE DRAWING

SHEET 3 OF 6

MODELS WITH BALLS



TOP



BALL

TopLine®

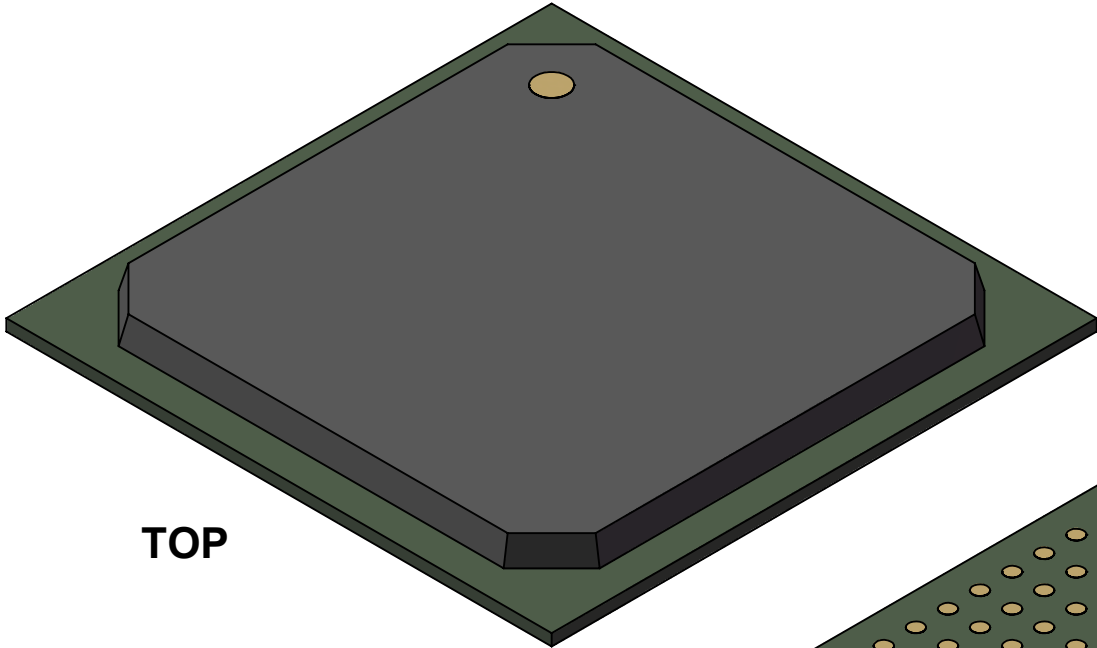
TITLE PGBA208T1.0C-DC164AD
DAISY CHAIN DUMMY

SCALE 6:1	SIZE A	DRAWING NO. 511641	REV A
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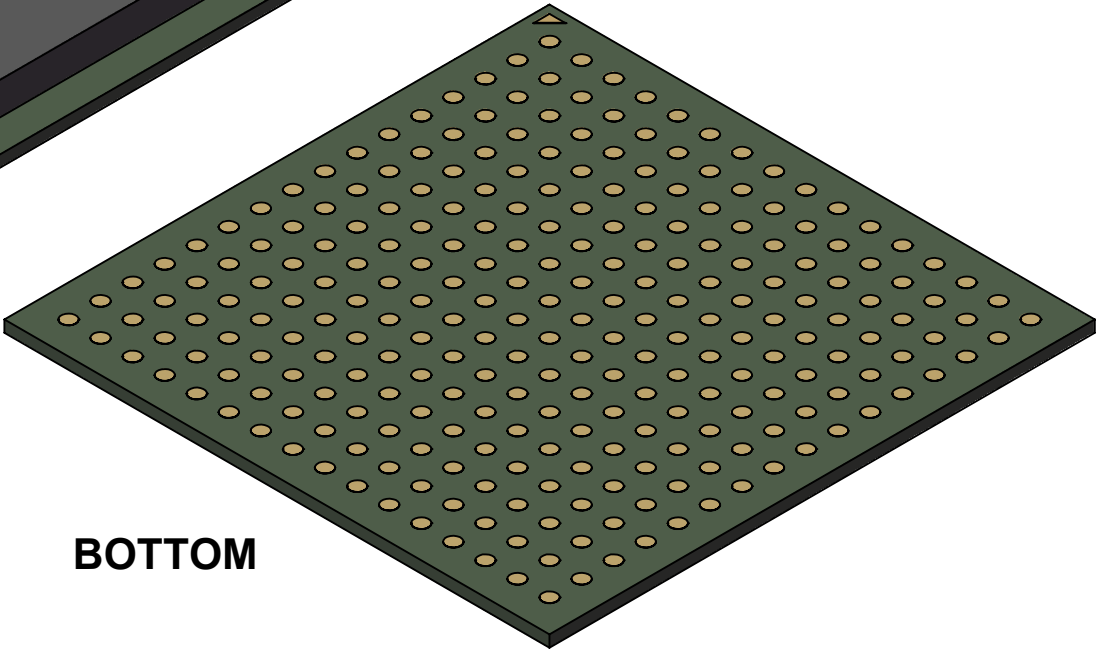
DO NOT SCALE DRAWING

SHEET 4 OF 6

MODELS
LGA WITHOUT BALLS



TOP

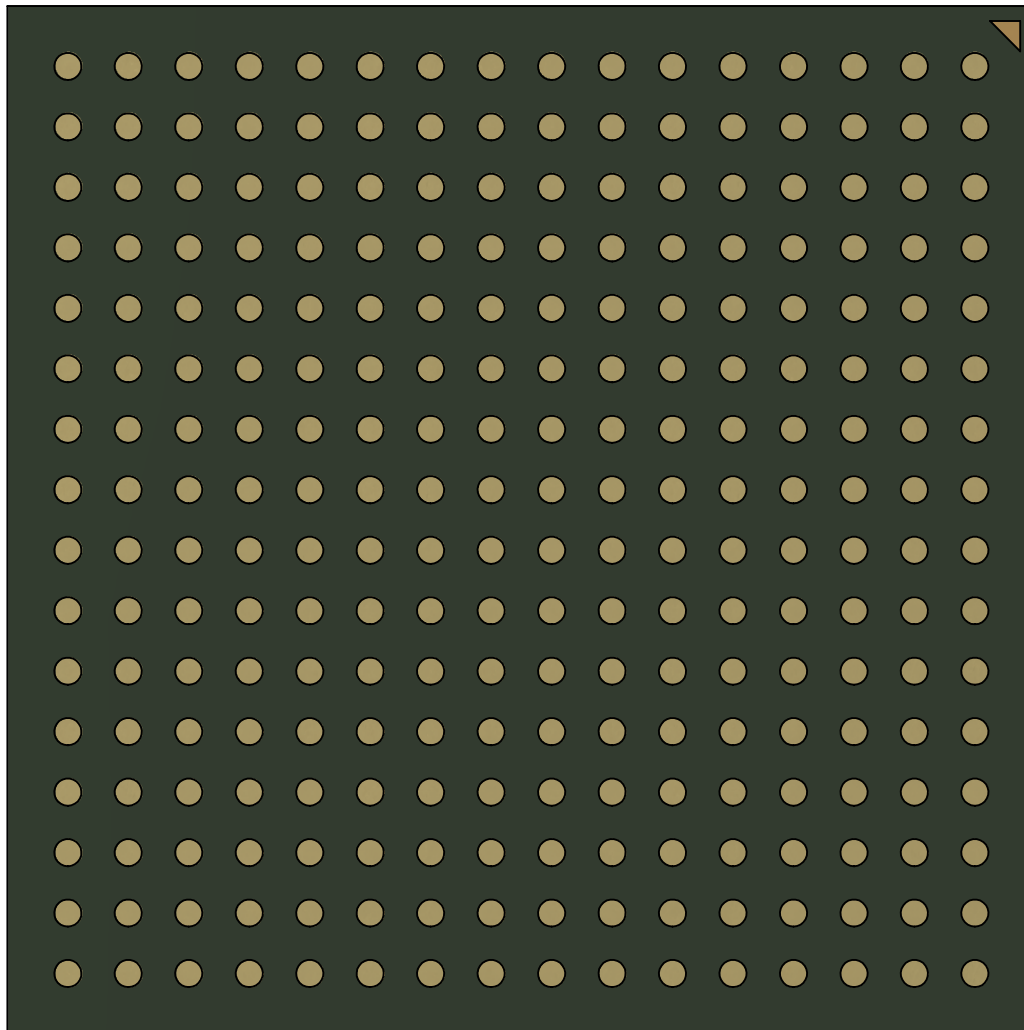


BOTTOM

TopLine[®]			
TITLE PGBA208T1.0C-DC164AD DAISY CHAIN DUMMY			
SCALE 6:1	SIZE A	DRAWING NO. 511641	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 6

BOTTOM SOLDER MASK (RIGHT READING)

16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1



A
B
C
D
E
F
G
H
J
K
L
M
N
P
R
T

TopLine®

TITLE PGBA208T1.0C-DC164AD
DAISY CHAIN DUMMY

SCALE 8:1	SIZE A	DRAWING NO. 511641	REV A
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DO NOT SCALE DRAWING

SHEET 6 OF 6